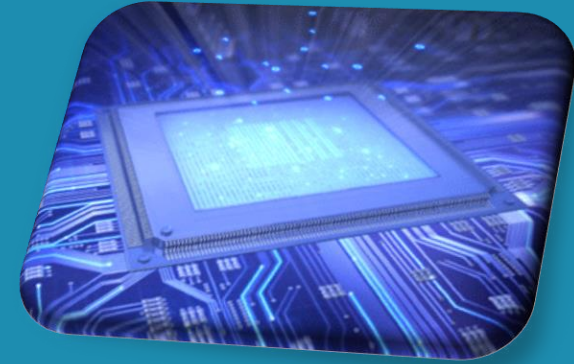


Impact of Aging Degradation Mechanisms on the Radiation Susceptibility of Complex Integrated Circuits

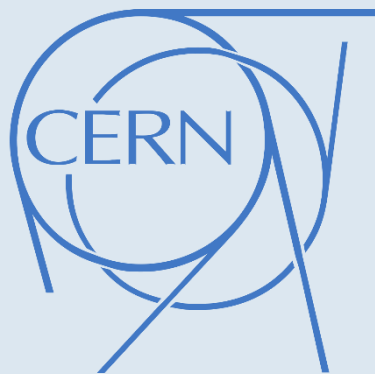


Mohamed Mounir

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RADSAGA Training Workshop March 2018



Reliability

- Reliability is essential for safe operation and optimized efficiency within most critical applications: (space, avionics, automotive, accelerators).



- **Radiation** effects on electronics are and have to be considered.



Long-term Reliability

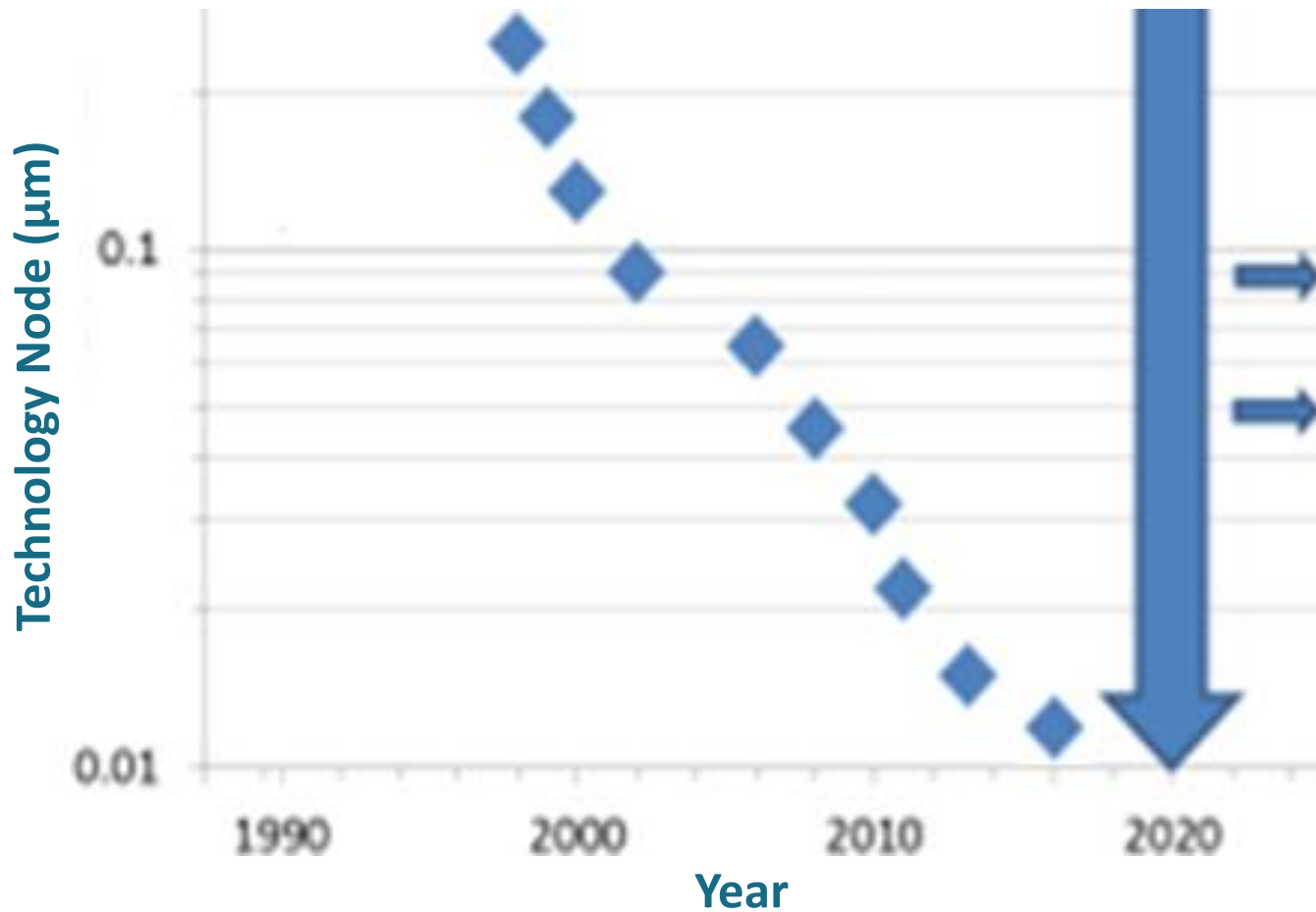
- Long-term reliability of recent CMOS technologies is impacted by different **intrinsic aging degradation mechanisms** that progressively change their electrical characteristics: (BTI, HCI, TDDB...).



- Degradation induced by these mechanisms constitutes a reliability risk, both directly, by compromising the electronic functions, and indirectly, by weakening the circuit robustness to external effects like **radiation**.



Long-term Reliability



Radiation effects due to neutrons

90 nm



45 nm

Wear out aging mechanisms impacting the product lifetime

Project Objective

- Investigate the impact of *aging degradation mechanisms* on the *radiation susceptibility* of digital integrated circuits in advanced technology.



- Develop *dynamic models* to **radiation effects**, taking into account the intrinsic performance degradation due to the diverse **aging mechanisms**.

Interdependence Between ESR



Collaboration with ST

- 28nm FD-SOI, is an innovative technology that leverages the established planar process while ensuring a continuation of the efficiency improvements projected by Moore's law.
- FD-SOI delivers:
 - die size reductions,
 - power reductions,
 - increases in performance,
 - increased functionality,without the need to add complex manufacturing.



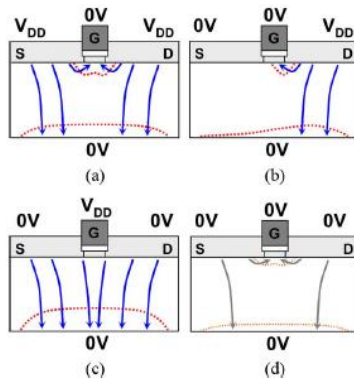
FD-SOI

Radiation Effects on FD-SOI

Trapped charges in BOX

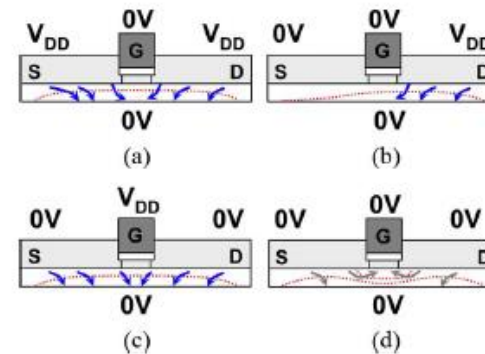
Thick BOX

1. More charge
2. Large V_{bb} shift
3. High variability across different devices



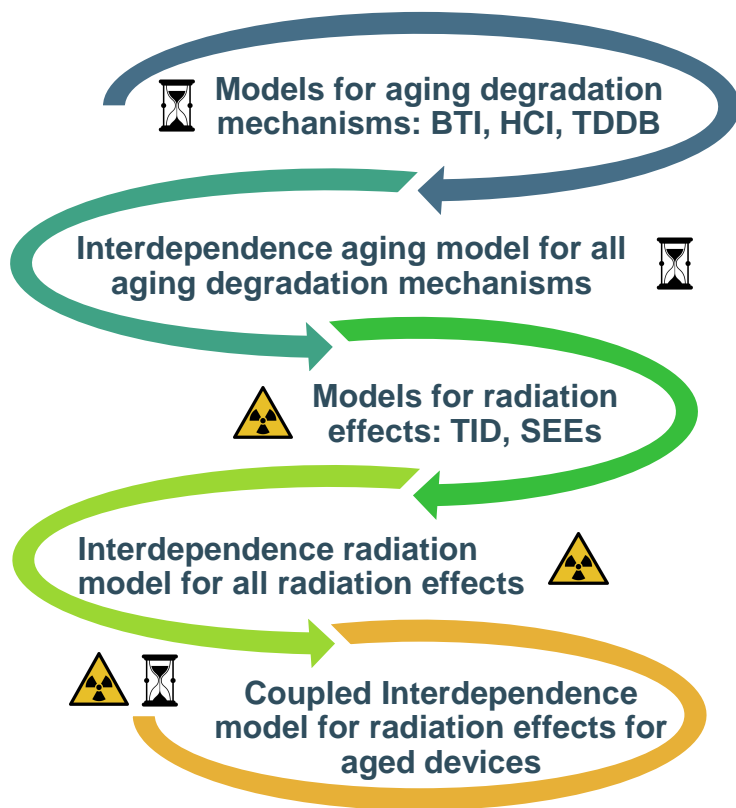
Ultra-thin BOX

1. Less charge
2. Small V_{bb} shift
3. Low variability

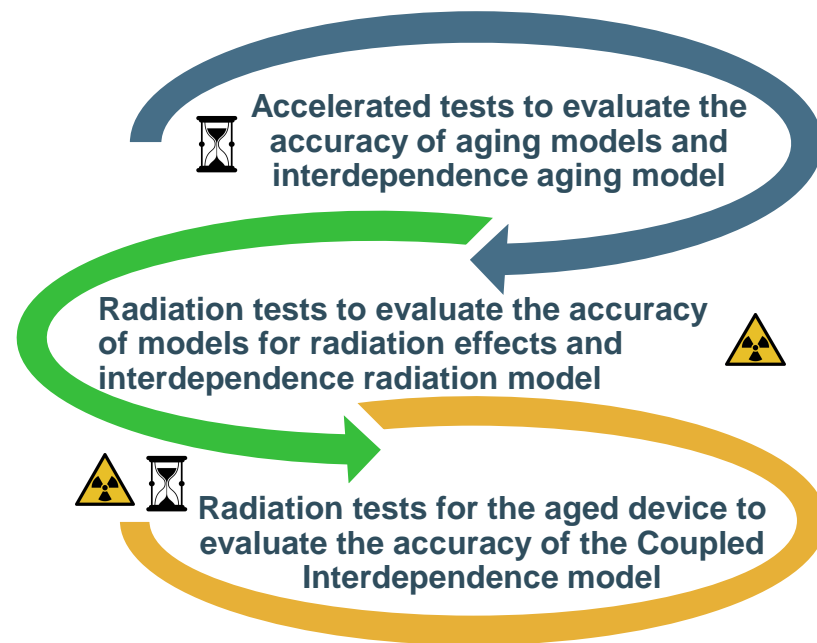


Project Plan

Develop Reliability Device Models



Accelerated Physical Tests



Progress

- Develop dynamic **Reaction-Diffusion model** for ***Bias Temperature Instability (BTI)*** aging degradation mechanism.
- BTI increases the delay of transistors over time, causing the circuits speed to decrease, and this leads to delay faults.
- BTI is represented by incremental shift in $|V_{th}|$.

Results

|V_{th}| Shift due to BTI aging degradation mechanism:

